



PK638 (v1.0) April 4, 2014

100% Material Declaration Data Sheet for Spartan 3A DSP CS484 Package

Average Weight: 1.3497g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.048956	3.627
	Silicon	7440-21-3	100.00		0.048956	
Silver Epoxy					0.014829	1.099
	Silver	7440-22-4	77.50		0.011492	
	Bismaleimide monomer	Trade Secret	15.00		0.002224	
	Acrylate monomer	Trade Secret	7.50		0.001112	
Mold Compound					0.453644	33.610
	Epoxy Resin	Trade Secret	7.50		0.034023	
	Phenol Resin A	9003-35-4	3.00		0.013609	
	Phenol Resin B	Trade Secret	3.00		0.013609	
	Silica(Amorphous)A	60676-86-0	67.95		0.308251	
	Silica(Amorphous)B	7631-86-9	15.00		0.068047	
	Metal Hydroxide	Trade Secret	3.00		0.013609	
	Carbon Black	1333-86-4	0.55		0.002495	
Copper Wire					0.003811	0.282
	Copper	7440-50-8	98.25		0.003744	
	Palladium	7440-05-3	1.75		0.000067	
Solder Ball					0.194345	14.399
	Tin	7440-31-5	63.00		0.122437	
	Lead	7439-92-1	37.00		0.071908	
Substrate					0.634127	46.982
	Gold	7440-57-5	0.12		0.000754	
	Nickel	7440-02-0	1.10		0.006956	
	Copper Foil	7440-50-8	52.40		0.332302	
	Copper Plating	7440-50-8	4.75		0.030201	
	BT Core	65997-17-3 / 105391-33-1 / 25722-66-1 / 9003-36-5 / 21645-51-2	37.02		0.234740	
	Solder Mask	34590-94-8 / 7727-43-7	4.60		0.029174	

© Copyright 2014 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/04/14	1.0	Initial Xilinx release.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.